Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
1	32	(south near epitaxy near corporation)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 11:57
L2	0	"10707084"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 11:57
L3	1	"10/707084"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 11:59
L4	3367	high near resistivity near2 layer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 11:59
L5	3367	high near resistivity near2 (interlaye or inter-layer or layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 11:59
L6	3368	high near resistivity near2 (interlayer or inter-layer or layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:00
L7	30	high near resistivity near2 (interlayer or inter-layer or layer) near2 GaN	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:00
L10	193	"Al.sub.xIn.sub.yGa.sub.1-x-yN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:25
L11	209	"Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:28

<u> </u>	T	T	I	,		
L12	1	((resistive or resistivity) near10 ("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub.	US-PGPUB; USPAT; EPO; JPO;	OR	ON	2007/04/23 12:27
		1-a-bN"))	DERWENT; IBM_TDB			
L13	2	((resistive or resistivity or interlayer) near10 ("Al.sub.xIn. sub.yGa.sub.1-x-yN" or "Al.sub.	US-PGPUB; USPAT; EPO; JPO;	OR	ON	2007/04/23 12:27
		aIn.sub.bGa.sub.1-a-bN"))	DERWENT; IBM_TDB			
L14	2	((resistive or resistivity or interlayer or inter-layer) near10 ("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:27
L15	2	((resistive or resistivity or interlayer or inter-layer) near10 (("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub.1-a-bN")))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:27
L16	36	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN") and nucleation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 12:28
L17	18	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN") and nucleation and electrode	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:43
L18	104	(sheu and lai)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:50
L19	3481	(257/184.ccls. or 257/190.ccls. or 257/452.ccls. or 257/457.ccls. or 257/459.ccls. or 257/461.ccls.)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:55
L20	355	l19 and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:51
L21	72	I19 and (leakage near current) and (high near (resistance or resistor or resistivity))	US-PGPUB; USPAT; EPO; JPO; DERWENT;	OR	ON	2007/04/23 13:52
4/22/07	4:52:55 PM		IBM_TDB			Раде 2

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L22	22	I19 and (leakage near current) same (high near (resistance or resistor or resistivity))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:53
L23	2	I19 and (leakage near current) same (high near (resistance or resistor or resistivity) same (nitride or gan or algan or alingan))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:54
L24	5	(257/184.ccls. or 257/190.ccls. or 257/452.ccls. or 257/457.ccls. or 257/459.ccls. or 257/461.ccls.) and ("Al.sub.xIn.sub.yGa.sub. 1-x-yN" or "Al.sub.aIn.sub.bGa. sub.1-a-bN")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:55
L25	5	(257/184.ccls. or 257/190.ccls. or 257/452.ccls. or 257/457.ccls. or 257/459.ccls. or 257/461.ccls.) and (("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub.1-a-bN"))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:56
L26		(257/184.ccls. or 257/190.ccls. or 257/452.ccls. or 257/457.ccls. or 257/459.ccls. or 257/461.ccls.) and (("Al.sub.xIn.sub.yGa.sub. 1-x-yN" or "Al.sub.aIn.sub.bGa. sub.1-a-bN")) and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:56
L27	30	((''Al.sub.xIn.sub.yGa.sub.1-x-yN'' or "Al.sub.aIn.sub.bGa.sub. 1-a-bN")) and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 13:57
L28	3	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN")) same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:16
L29	340	((''Al:sub:xIn:sub:yGa.sub:1-x-yN'' or "Al:sub:aIn:sub:bGa.sub: 1-a-bN'' or AlInGaN or GaN)) same (leakage:near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:17
L30	69	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN)) near10 layer near10 (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:20

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L31	89	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (indirum near2 aluminum near2 gallium near2 nitride))) near10 layer with (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:20
L32	205	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (indirum near2 aluminum near2 gallium near2 nitride))) near10 layer same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:22
L33	1066	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (indirum near2 aluminum near2 gallium near2 nitride) or ((resistor or resistive or resistivity or resistance) near2 layer))) near10 layer same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:21
L34	1238	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indirum near2 aluminum near2 gallium near2 nitride))) near10 layer same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:22
L35	1238	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) near10 layer same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:23
L36	444	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) near10 layer near10 (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:22
L37	862412	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:24

L38	29769	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:24
L39	47118	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (resistance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:24
L40	20478	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (resistance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:24
L41	352	(("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or AlInGaN or GaN or (resistance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) same (leakage near current) and nucleation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:26
L42	1814	(electrode same (semiconductor near layer) same (active near layer) and ohmic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:27
L43	996	(electrode same (semiconductor near layer) same (active near layer) same ohmic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:27
L44	74	(electrode same (semiconductor near layer) same (active near layer) same ohmic same ("Al.sub. aIn.sub.bGa.sub.1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride)))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:29

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L45	2	(electrode same (semiconductor near layer) same (active near layer) same ohmic same ("Al.sub. aIn.sub.bGa.sub.1-a-bN" or AlInGaN or GaN or (ressitance or	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:29
		resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) and (leakage near current)				
L46	56	(electrode same (semiconductor near layer) same (active near layer) same ("Al.sub.aIn.sub.bGa. sub.1-a-bN" or AlInGaN or GaN or (ressitance or resistive or resistivity or resistor) or (indium near2 aluminum near2 gallium near2 nitride))) and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:33
L47	164	("Al.sub.aIn.sub.bGa.sub.1-a-bN" or AlInGaN or (indium near2 aluminum near2 gallium near2 nitride)) and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON ·	2007/04/23 14:36
L48	0	"Al:sub.xIn.sub.yGa.sub.1-x-yN" near10 leakage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:35
L49	0	"Al.sub.xIn.sub.yGa.sub.1-x-yN" with leakage	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:35
L50	193	"Al.sub.xIn.sub.yGa.sub.1-x-yN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:36
L51	3	"Al.sub.xIn.sub.yGa.sub.1-x-yN" same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:38
L52	3	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN") same (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:59

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L53	30	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN") and (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:39
L54	6	("Al:sub:xIn:sub.yGa.sub.1-x-yN" or "Al:sub:aIn:sub.bGa.sub. 1-a-bN") and (leakage near current) and nucleation	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:39
L55	0	I52 and (strangulation same (dope or doped or doping))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 14:59
L56	357743	((highly or high) near2 (resistivity or resistance or resistor or resistive))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:04
L57	1867	((highly or high) near2 (resistivity or resistance or resistor or resistive)) with (leakage near current)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:04
L58	О	((highly or high) near2 (resistivity or resistance or resistor or resistive)) with (leakage near current) with "Al.sub.xIn.sub.yGa. sub.1-x-yN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:05
L59	0	((highly or high) near2 (resistivity or resistance or resistor or resistive)) with (leakage near current) same "Al.sub.xIn.sub. yGa.sub.1-x-yN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:05
L60	0	((highly or high) near2 (resistivity or resistance or resistor or resistive)) same (leakage near current) same "Al.sub.xIn.sub. yGa.sub.1-x-yN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:05
L61	0	(((highly or high) near2 (resistivity or resistance or resistor or resistive)) or high-resistivity) same (leakage near current) same "Al. sub.xIn.sub.yGa.sub.1-x-yN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:05
L62	5	(((highly or high) near2 (resistivity or resistance or resistor or resistive)) or high-resistivity) same "Al.sub.xIn.sub.yGa.sub.1-x-yN"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:06

162	300	"Al cub vTa cub vCa cub 1 x vAIII	HC DCDUD.	OB	ONI	2007/04/22 15:07
L63	209	"Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub.	US-PGPUB; USPAT;	OR	ON	2007/04/23 15:07
		1-a-bN"	EPO; JPO;			
		1-0-014	DERWENT;			
			IBM_TDB			
L64	30	("Al.sub.xIn.sub.yGa.sub.1-x-yN"	US-PGPUB;	OR	ON	2007/04/23 15:59
		or "Al.sub.aIn.sub.bGa.sub.	USPAT;			
		1-a-bN") and (leakage near	EPO; JPO;			
		current)	DERWENT;			
			IBM_TDB			
L65	1	I64 and ((current near2	US-PGPUB;	OR	ON	2007/04/23 15:52
		strangulation) near10 (implant or	USPAT;			
;		implanting or implanted or	EPO; JPO;			
		implantation))	DERWENT;			
40 * 1 * 1 * 1 * 1 * 1 * 1 * 1 * 1 * 1 *	50-15-0-00 500 500 500 500 500 500		IBM_TDB	,		100000000000000000000000000000000000000
L66	40	(US-20040080010-\$ or	US-PGPUB;	OR	ON	2007/04/23 15:58
		US-20030062525-\$ or	USPAT;			
		US-20030015708-\$ or	JPO;			
		US-20030146444-\$ or	DERWENT			
		US-20050012113-\$ or				
		US-20020074553-\$ or				
		US-20030218183-\$ or US-20060199289-\$ or				
		US-20060226417-\$ or				
		US-20030122147-\$ or				
		US-20020096687-\$ or				
		US-20030127658-\$ or				
		US-20030214807-\$ or				
		US-20050082543-\$ or				
		US-20050167680-\$ or				
		US-20050274964-\$ or				
		US-20030071276-\$ or				
		US-20030047744-\$ or				
		US-20050167697-\$).did. or (US-6586272-\$ or US-5677538-\$				
		or US-5598014-\$ or US-6455340-\$				
		or US-5847397-\$ or US-6495852-\$				
		or US-6429467-\$ or US-5977565-\$				
		or US-5932905-\$ or US-5717235-\$				
		or US-5707887-\$ or US-5507881-\$				
		or US-6208074-\$ or US-5673220-\$				
		or US-7151281-\$).did. or				
		(JP-06216404-\$).did. or				
		(US-20030230235-\$ or				
		US-20050032345-\$ or				
		JP-06216404-\$ or				
		US-20050012113-\$ or				
		EP-296371-\$).did.				

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L67	71	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN") same (active near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 15:59
L68	73	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") same (active near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:00
L69	35	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 (active near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:00
L70	69	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 ((semiconductor or active) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:06
L71	1	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 ((semiconductor or active) near layer) and (electrode near10 (finger or interlaced))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:04
L72	1	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 ((semiconductor or active) near layer) and ((finger-shaped or finger or interlaced))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:04
L73	26	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 ((semiconductor or active) near layer).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:04
L74		("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 ((semiconductor or active) near layer) and ("Al.sub.xIn.sub.yGa. sub.1-x-yN" or "Al.sub.aIn.sub. bGa.sub.1-a-bN" or "Al.sub.eIn. sub.fGa.sub.1-e-fN") near10 ((nucleation or buffer) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:08

L75	4	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN") near10 ((semiconductor or active) near layer) and ("Al.sub.xIn.sub.yGa. sub.1-x-yN" or "Al.sub.aIn.sub. bGa.sub.1-a-bN" or "Al.sub.eIn. sub.fGa.sub.1-e-fN") near10 ((nucleation or buffer) near layer) and ("Al.sub.xIn.sub.yGa.sub. 1-x-yN" or "Al.sub.aIn.sub.bGa. sub.1-a-bN" or "Al.sub.eIn.sub. fGa.sub.1-e-fN") near10 ((clad or contact) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:08
L76	4	("Al:sub:xIn:sub:yGa:sub:1-x-yN" or "Al:sub:aIn:sub:bGa:sub: 1-a-bN" or "Al:sub:eIn:sub:fGa: sub:1-e-fN") near10 ((semiconductor or active) near layer) and ("Al:sub:xIn:sub:yGa: sub:1-x-yN" or "Al:sub:aIn:sub:bGa:sub:1-a-bN" or "Al:sub:eIn: sub:fGa:sub:1-e-fN") near10 ((nucleation or buffer) near layer) and ("Al:sub:xIn:sub:yGa:sub: 1-x-yN" or "Al:sub:aIn:sub:bGa: sub:1-a-bN" or "Al:sub:eIn:sub:fGa:sub:1-e-fN") near10 ((cladding or clad or contact) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:09
L77	5	("Al.sub.xIn.sub.yGa.sub.1-x-yN" or "Al.sub.aIn.sub.bGa.sub. 1-a-bN" or "Al.sub.eIn.sub.fGa. sub.1-e-fN" or "Al.sub.cIn.sub. dGa.sub.1-c-dN") near10 ((semiconductor or active) near layer) and ("Al.sub.xIn.sub.yGa. sub.1-x-yN" or "Al.sub.aIn.sub. bGa.sub.1-a-bN" or "Al.sub.eIn. sub.fGa.sub.1-e-fN" or "Al.sub.cIn. sub.dGa.sub.1-c-dN") near10 ((nucleation or buffer) near layer) and ("Al.sub.xIn.sub.yGa.sub. 1-x-yN" or "Al.sub.aIn.sub.bGa. sub.1-a-bN" or "Al.sub.eIn.sub. fGa.sub.1-e-fN" or "Al.sub.eIn.sub. dGa.sub.1-c-dN") near10 ((cladding or clad or contact) near layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:10

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L78	41	(US-20040080010-\$ or	US-PGPUB;	OR	ON	2007/04/23 16:25
		US-20030062525-\$ or	USPAT;			_
		US-20030015708-\$ or	JPO;			
1 (US-20030146444-\$ or	DERWENT		,	
		US-20050012113-\$ or				
		US-20020074553-\$ or				
		US-20030218183-\$ or				
		US-20060199289-\$ or				
		US-20060226417-\$ or				
	į	US-20030122147-\$ or				<u>;</u>
		US-20020096687-\$ or				
		US-20030127658-\$ or				
		US-20030214807-\$ or				
		US-20050082543-\$ or				
		US-20050167680-\$ or				
		US-20050274964-\$ or				
		US-20030071276-\$ or		1		
		US-20030047744-\$ or				
		US-20050167697-\$ or				
		US-20040124435-\$).did. or				
		(US-6586272-\$ or US-5677538-\$				
		or US-5598014-\$ or US-6455340-\$				
		or US-5847397-\$ or US-6495852-\$				
		or US-6429467-\$ or US-5977565-\$			ļ	
		or US-5932905-\$ or US-5717235-\$				
		or US-5707887-\$ or US-5507881-\$				
		or US-6208074-\$ or US-5673220-\$				
		or US-7151281-\$).did. or				
		(JP-06216404-\$).did. or				
		(US-20030230235-\$ or				
		US-20050032345-\$ or			•	
		JP-06216404-\$ or				
		US-20050012113-\$ or				
		EP-296371-\$).did.				
	F1) - 8,88678-99179999-9888					
L79	4	I78 and (electrode near10 (finger	US-PGPUB;	OR	ON	2007/04/23 16:28
		or finger-shaped or interlaced))	USPAT;			
			EPO; JPO;			
			DERWENT;			
			IBM_TDB			
L80	4	178 and (electrode near10 (finger	US-PGPUB;	OR	ON	2007/04/23 16:28
	•	or finger-shaped or interlaced) or	USPAT;			2007/01/23 10.20
		interdigitated)	EPO; JPO;			
		interalgitatedy	DERWENT;			
			T i			
			IBM_TDB			
L81	25234	(electrode near10 (finger or	US-PGPUB;	OR	ON	2007/04/23 16:28
		finger-shaped or interlaced) or	USPAT;			
		interdigitated)	EPO; JPO;			
			DERWENT;			
			IBM_TDB			

L82	' 192 ·	((nucleation or buffer) near layer) and ((active or semicondcutor) near layer) and (electrode near10 (finger or finger-shaped or interlaced) or interdigitated)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:29
L83	134	((nucleation or buffer) near layer) and ((active or semicondcutor) near layer) and ((contact or clad or cladding) near layer) and (electrode near10 (finger or finger-shaped or interlaced) or interdigitated)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:30
L84	77	((nucleation or buffer) near layer) and ((active or semicondcutor) near layer) and ((contact or clad or cladding) near layer) and (electrode near10 (finger or finger-shaped or interlaced) or interdigitated) and nitride	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:30
L85	78	((nucleation or buffer) near layer) and ((active or semicondcutor) near layer) and ((contact or clad or cladding) near layer) and (electrode near10 (finger or finger-shaped or interlaced) or interdigitated) and (nitride or GaN)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/04/23 16:30